

Product End-of-Life Instructions

PRODUCT FAMILY

Studio Desktops

PURPOSE

The intent of this document is to provide guidance to recyclers on the presence of materials and components at the product / family level, as required by the EU WEEE Directive 2012/19/EU. This document should also help direct recyclers to proper methods for removing parts and general product disassembly instructions.

PRODUCT DISASSEMBLY INSTRUCTIONS

Most parts can be removed easily by hand. In some cases common household tools such as Philips and/or flat-head screw drivers may be necessary. To remove discrete components such as the electrolytic capacitors, needle-nose pliers may be helpful. Instructions for removing parts in each product can be found in the User Documentation originally provided with the product. This documentation can be found online:

https://www.dell.com/support/home/en-us/products/desktop/desktop_legacy/desktop_studio_legacy

PRODUCT MATERIAL INFORMATION

The following substances, preparations, or components should be disposed of or recovered separately from other WEEE in compliance with Article 4 of EU Council Directive 75/442/EEC.

	Mercury	Dell does not use internal batteries based on Mercury (Hg) and its compounds.	
Batteries	Cadmium	Dell does not use internal batteries based on Cadmium (Cd) and its compounds.	
	Lead	Dell does not use internal batteries based on Lead (Pb) and its compounds.	
	Other	This product uses a Lithium Primary Coin Cell Battery	
Mercury	Lamps, Bulbs, and other Lighting Applications	Product does not contain a Mercury based lamp or bulb.	
	Other Uses	Other parts used in Dell products can not contain intentionally added Mercury.	
Liquid Crystal Displays (LCD) - > 100 cm2		Product does not contain an LCD greater than 100 cm2.	
Cathode Ray Tubes (CRT)		Product does not contain a CRT	
Plastic containing Brominated flame retardants other than in PCB / PCA			



	This product may contain plastic parts with Brominated flame retardants. Plastic parts location can be visually identified by their typical design function for the product (also shown in the service manual). See reference plastic list
	Many of these parts (Greater than 25 grams) are bromine free. Regardless, these parts are labeled (usually molded directly into the plastic) per ISO 11469: A typical label would look like: > Polymer Abbreviation - FR(#) < i.e. > PC+ABS FR(40) <
	Flame retardant codes (FR(#)) are given in ISO 1043-4. Codes for some Brominated flame retardants: 14 aliphatic/alicyclic Brominated compounds
	15 aliphatic/alicyclic Brominated compounds in combination with antimony compounds16 aromatic Brominated compounds (excluding Brominated
	diphenyl ether and biphenyls) 17 aromatic Brominated compounds (excluding Brominated diphenyl ether and biphenyls) in combination with antimony
	compounds 22 aliphatic/alicyclic chlorinated and Brominated compounds
	42 Brominated organic phosphorus compounds Plastics parts weighing less than 25 grams may or may not contain
	brominated flame retardants. These smaller plastics parts may include: Fan impeller, speaker, keycaps, thermal plate, plastics in power adapter (may be applicable to Micro and Ultra Small form factor desktops)
	Recycler should treat these parts separately. For more information contact support or visit: https://support.dellproductcompliance.com/hc/en-us
Capacitors with PCB's	Dell does not use capacitors with PCB
Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)	Present in the product as system board, wireless card, Hard disk drive/Solid State drives, graphics card, power adapter (may be applicable to Micro and Ultra Small form factor desktops)
Electrolyte capacitors (height > 25mm, diameter > 25mm)	Electrolytic capacitors (height and/or diameter greater than 25mm) are not used on Dell motherboards. However, these capacitors are often present in power supply units (silver box).
External Electric cables	May be present. (e.g power cord)
Asbestos and its compounds	Parts used in Dell products cannot contain asbestos or its compounds
Refractory ceramic fibers	Parts used in Dell products cannot contain refractory ceramic fibers

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Radio-active substances	Parts used in Dell products cannot contain Radio-active substances.
Beryllium and its compounds (including Beryllium Oxide)	Beryllium may be present in electronic components as a copper beryllium alloy, which contains less than 2% beryllium. CuBe alloys may be used in various components such as connectors, switches, relays, current carrying springs, integrated circuit sockets, and RF shielding.
Gasses - which fall under Regulation (EC) 2037/2000 and all hydrocarbons (HC)	Parts used in Dell products do not contain gasses which fall under Regulation (EC 2037/2000) and all hydrocarbons (HC).
Components with pressurized gas which need special attention (Pressure > 1,5bar)	Product does not contain parts with pressurized gas.
Liquids	This product may contain a heatsink heat pipe. Heat pipes contain a very small amount of very pure water.

DELL CORPORATE ENVIRONMENTAL INFORMATION

Information on Dell's Environmental initiatives, policies, programs and goals can be found at www.dell.com/environment.

Representative plastics reference list*

Representative plastics reference list				
Plastic Part name	Picture	Location Description		
Side Cover		Houses and shields the electronic components underneath.		
Front Bezel		The front of the computer.		



Hard Drive Bracket	Part of the hard drive assembly, inside the HDD filler bracket
Speaker	Inside front panel door.
Heat Sink Fan	As shown in picture, centrally located on the system board under the front panel door.



System Fan	As shown here at back of computer on paneling
Keyboard & Mouse (Optional)	The keyboard and mouse are external to the Desktop

^{*}Some parts may not be applicable to all products in this family or may be made with material other than plastics